

# PROCEEDINGS OF SPIE

## ***Laser 3D Manufacturing III***

**Bo Gu**  
**Henry Helvajian**  
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*Editors*

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# Contents

- vii *Authors*
- ix *Conference Committee*
- xi *Industry Panel*
- xiii *Introduction*

---

## LASER 3D MICRO/NANO STRUCTURING: JOINT SESSION WITH CONFERENCES 9735 AND 9738

- 9738 03 **Improvement in contact resistance of 4H-SiC by excimer laser doping using silicon nitride films [9738-1]**
- 9738 04 **A cantilever based optical fiber acoustic sensor fabricated by femtosecond laser micromachining [9738-2]**

---

## LASER DIRECT WRITING: JOINT SESSION WITH CONFERENCES 9735 AND 9738

- 9738 05 **Laser-assisted inkjet printing of highly viscous fluids with sub-nozzle resolution [9738-3]**
- 9738 06 **Laser printing and femtosecond laser structuring of electrode materials for the manufacturing of 3D lithium-ion micro-batteries [9738-4]**

---

## 3D LASER STRUCTURING DEVICES AND LITHOGRAPHY III: JOINT SESSION WITH CONFERENCES 9738 AND 9759

- 9738 08 **Precise 3D printing of micro/nanostructures using highly conductive carbon nanotube-thiol-acrylate composites [9738-6]**
- 9738 09 **Potential for GPC-based laser direct writing [9738-7]**

---

## 3D LASER STRUCTURING DEVICES AND LITHOGRAPHY IV: JOINT SESSION WITH CONFERENCES 9738 AND 9759

- 9738 0A **3D light robotics (Invited Paper) [9738-8]**
- 9738 0C **Advanced two-photon photolithography for patterning of transparent, electrically conductive ionic liquid-polymer nanostructures (3D Printing Best Paper Award) [9738-10]**

---

**LASER INDUCED FORWARD TRANSFER (LIFT)**

---

9738 0I **Laser printing of 3D metallic interconnects** [9738-12]

---

**MATERIALS, PROCESSES, AND POST-PRINTING PROCESSES FOR ADDITIVE MANUFACTURING**

---

9738 0K **3D manufacturing of micro and nano-architected materials (Invited Paper)** [9738-14]

9738 0O **Review on laser powder injection additive manufacturing of novel alloys and composites (Invited Paper)** [9738-18]

---

**MODELING, DESIGN, PROCESS MONITORING, AND CONTROLS FOR ADDITIVE MANUFACTURING**

---

9738 0Q **Towards in-situ process monitoring during additive manufacturing using optical coherence tomography** [9738-20]

9738 0R **Sensing for directed energy deposition and powder bed fusion additive manufacturing at Penn State University (Invited Paper)** [9738-21]

9738 0S **Optical design and initial results from NIST's AMMT/TEMPS facility** [9738-22]

9738 0T **Towards photo-induced swimming: actuation of liquid crystalline elastomer in water (Invited Paper)** [9738-23]

---

**SLM, DMLS, SLS, SLM WITH ULTRAFAST LASERS**

---

9738 0U **Femtosecond fiber laser additive manufacturing of tungsten (Invited Paper)** [9738-24]

9738 0W **Laser post-processing of Inconel 625 made by selective laser melting** [9738-26]

9738 0X **Fabrication and heat treatment of high strength Al-Cu-Mg alloy processed using selective laser melting** [9738-27]

---

**APPLICATIONS, SYSTEMS, PROCESS DEVELOPMENTS FOR ADDITIVE MANUFACTURING I**

---

9738 0Y **Additive manufacturing of glass for optical applications (3D Printing Best Paper Award)** [9738-28]

9738 0Z **Reducing residual stresses and deformations in selective laser melting through multi-level multi-scale optimization of cellular scanning strategy** [9738-29]

9738 10 **Application of laser ultrasonic non-destructive evaluation technique to additive manufacturing** [9738-30]

9738 11 **Repurposing mainstream CNC machine tools for laser-based additive manufacturing (Invited Paper)** [9738-31]

---

**APPLICATIONS, SYSTEMS, PROCESS DEVELOPMENTS FOR ADDITIVE MANUFACTURING II**

---

- 9738 13 **X-band printed phased array antennas using high-performance CNT/ion gel/Ag transistors (Invited Paper)** [9738-34]
- 9738 16 **The application of digital medical 3D printing technology on tumor operation (Invited Paper)** [9738-37]

---

**POSTER SESSION**

---

- 9738 17 **Experiments for practical education in process parameter optimization for selective laser sintering to increase workpiece quality** [9738-38]
- 9738 1B **Improving accuracy of overhanging structures for selective laser melting through reliability characterization of single track formation on thick powder beds** [9738-44]
- 9738 1C **Experimental study on Ti alloy plate fabrication by vacuum selective laser melting** [9738-45]



# Authors

Numbers in the index correspond to the last two digits of the six-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first four digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Abe, Nobuyuki, 1C  
Asano, T., 03  
Auyeung, Raymond C. Y., 0I  
Bai, Shuang, 0U  
Bakhtina, Natalia A., 0C  
Bañas, Andrew, 09, 0A  
Banks, Jeffery C., 0R  
Bayer, Natascha, 17  
Beniam, Iyoel, 0I  
Bidoky, Fazel, 13  
Bristow, Douglas A., 0Y  
Brown, Stephen W., 0R  
Cerretti, Giacomo, 0T  
Charipar, Nicholas A., 0I  
Chen, Jimin, 16  
Chen, Ray T., 13  
Childs, David T. D., 0Q  
Clare, Adam T., 0Q  
Clemon, L., 0O  
Delrot, Paul, 05  
Drauschke, Andreas, 17  
Feck, David P., 0R  
Fischer, Peer, 0T  
Frisbie, Daniel, 13  
Gaiser, K., 0O  
Gilbert, Luke J., 0Y  
Glückstad, Jesper, 09, 0A  
Goldstein, Jonathan T., 0Y  
Goodridge, Ruth, 0Q  
Grantham, Steven, 0S  
Groom, Kristian M., 0Q  
Grubb, Peter Mack, 13  
Guan, Guangying, 0Q  
Hansen, William, 0W  
Hanssen, Leonard, 0S  
Hattel, Jesper Henri, 0Z, 1B  
Helvajian, Henry, 0W, 10  
Hirsch, Matthias, 0Q  
Hu, Zhiheng, 0X  
Huang, Huan, 0U  
Huang, Jie, 04  
Ikeda, A., 03  
Ikenoue, H., 03  
Jiang, L. J., 08  
Jiang, Yijian, 16  
Jones, Jason B., 11  
Kenderian, Shant, 10  
Kim, H., 06  
Kinzel, Edward C., 0Y  
Kojima, R., 03  
Korvink, Jan G., 0C  
Landers, Robert G., 0Y  
Lane, Brandon, 0S  
Lavernia, E. J., 0O  
Li, Wentao, 13  
Li, Yangsheng, 16  
Liu, Jian, 0U  
Liu, Jie, 04  
Liu, Y., 08  
Lu, W. Y., 0O  
Lu, Y. F., 08  
Lu, Zeng Hai, 0Q  
Luo, Junjie, 0Y  
MacKinnon, Neil, 0C  
Mahajan, Ankit, 13  
Manzo, Anthony J., 10  
Mark, Andrew G., 0T  
Martella, Daniele, 0T  
Masuno, Shinichiro, 1C  
Matcher, Stephen J., 0Q  
Mathews, Scott A., 0I  
Mekhonstev, Sergey, 0S  
Melde, Kai, 0T  
Modestino, Miguel A., 05  
Mohanty, Sankhya, 0Z, 1B  
Morgan, Jacob P., Jr., 0R  
Morgan, Jr., John P., 0R  
Moser, Christophe, 05  
Nakamura, D., 03  
Nassar, Abdalla R., 0R  
Natale, Donald J., 0R  
Neira, Jorge, 0S  
Nie, Xiaojia, 0X  
Okada, T., 03  
Palagi, Stefano, 0T  
Palima, Darwin, 0A  
Parmeggiani, Camilla, 0T  
Pflieger, W., 06  
Piqué, Alberto, 06, 0I  
Psaltis, Demetri, 05  
Qi, Ting, 0X  
Qiu, Tian, 0T  
Reutterer, Bernd, 17  
Reutzel, Edward W., 0R  
Sato, Yuji, 1C  
Schoenung, J. M., 0O  
Seifert, H. J., 06  
Smyrek, P., 06

Steffeney, Lee, 0W  
Subbaraman, Harish, 13  
Suwa, M., 03  
Traxler, Lukas, 17  
Tsukamoto, Masahiro, 1C  
Tutwiler, Rick L., 0R  
Urbas, Augustine M., 0Y  
Valdevit, Lorenzo, 0K  
Villangca, Mark, 0A  
Vlasea, Mihaela, 0S  
Wiersma, Diederik S., 0T  
Witkin, David, 0W  
Xiao, Hai, 04  
Xiong, W., 08  
Yamashita, Yorihiro, 1C  
Yang, Lih-Mei, 0U  
Yang, N., 0O  
Yang, Pei, 0U  
Yee, J., 0O  
Yuan, Lei, 04  
Zeng, Hao, 0T  
Zeng, Xiaoyan, 0X  
Zhai, Meiyu, 0U  
Zhang, Hu, 0X  
Zheng, B., 0O  
Zheng, Y., 06  
Zhou, Y. S., 08  
Zhou, Y., 0O  
Zhu, Haihong, 0X

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  - 4 3D Laser Structuring Devices and Lithography II: Joint Session with Conferences 9738 and 9759  
**Georg von Freymann**, Technische Universität Kaiserslautern (Germany)
  - 5 3D Laser Structuring Devices and Lithography III: Joint Session with Conferences 9738 and 9759  
**Winston V. Schoenfeld**, CREOL, The College of Optics and Photonics, University of Central Florida (United States)
  - 6 3D Laser Structuring Devices and Lithography IV: Joint Session with Conferences 9738 and 9759  
**Michael Thiel**, Nanoscribe GmbH (Germany)
- Industry Panel on 3D Printing: Outlook and Opportunities  
**Bo Gu**, Bos Photonics (United States)
- 7 Laser Induced Forward Transfer (LIFT)  
**Craig Goldberg**, Newport Corporation (United States)
  - 8 Materials, Processes, and Post-Printing Processes for Additive Manufacturing  
**Henry Helvajian**, The Aerospace Corporation (United States)
  - 9 Modeling, Design, Process Monitoring, and Controls for Additive Manufacturing  
**Alberto Piqué**, U.S. Naval Research Laboratory (United States)
  - 10 SLM, DMLS, SLS, SLM with Ultrafast Lasers  
**Alberto Piqué**, U.S. Naval Research Laboratory (United States)
  - 11 Applications, Systems, Process Developments for Additive Manufacturing I  
**Jian Liu**, PolarOnyx, Inc. (United States)
  - 12 Applications, Systems, Process Developments for Additive Manufacturing II  
**Bo Gu**, Bos Photonics (United States)

# Industry Panel on 3D Printing: Outlook and Opportunities



*Industry panel in session*

Kick off the 3D conference with this informative business session.

Market analysts valued the global 3D printing market at \$2.3B in 2013 and are projecting global revenues of \$8.6B by 2020 — an impressive compound annual growth rate of more than 20% over seven years! At the same time, Siemens estimates that 3D printing will become 50% less expensive and 400% faster over the next five years.

However, 3D printing can only reach its economic potential and fulfill its promise of revolutionizing manufacturing across multiple industries if a number of significant real-world structural challenges are addressed. Hurdles to widespread implementation of 3D printing include implementation of a proper regulatory framework, provisions to protect intellectual property, and establishment of appropriate standards and certification, to name a few.

Many joined us for a panel discussion about these hurdles and how they might be overcome. Expert perspectives on 3D printing technology, cyber security, intellectual property, and other key elements were addressed, as well as the widespread adoption of 3D printing. Industry leaders shared their views on the outlook for 3D printing and what they think needs to happen for digital manufacturing to go mainstream and fulfill its promise to create a broad range of new opportunities.

## **SPEAKERS/PANELISTS:**



*3D Printing Will Rock the World* **John F. Hornick**  
Partner, Finnegan, Henderson, Farabow, Garrett & Dunner, L.L.P.  
(United States)



*Smart Additive Manufacturing Systems (S-AMS)* **Jyoti Mazumder**  
Univ. of Michigan (United States)



*3D Printing and the Future of Manufacturing* **John D. Murray**  
Concept Laser, Inc. (United States)



*Cyber Security Concerns in 3D Printing* **Rebecca R. Taylor**  
Senior Vice President for the National Center for Manufacturing Sciences (NCMS)  
(United States)

Panel Discussion with Q&A followed



*Award recipients with one of the conference chairs*



*This year's panelists with the conference chairs*

## Introduction

Potentially a disruptive game changer, Laser Additive Manufacturing (LAM), or 3D Laser Printing as it is commonly known, has captured the popular imagination. While LAM is still a relatively new technology and definitely needs further development, it has already been disrupting the manufacturing value chain and allowing a path to mass producing customized products. In some applications, it has already reached a tipping point of maturity. However, to fully reach LAM economic potential and to fulfill its promise to create wealth it takes much more than just pure technological development. There are enormous challenges remained to be tackled: regulatory framework, intellectual properties, product liabilities, standardization and certification, cyber security to name just a few.

The Laser 3D Manufacturing Conference at Photonics West was very unique. It provided a forum for professionals from multiple disciplines to share and discuss the latest advances in the field of laser-based digital manufacturing and the development and implementation of next generation laser-based 3D manufacturing processes. We believe this type of cross talk and communication amongst conference speakers and attendees from all fields related to LAM (which include material science, laser processing physics/chemistry, mechanical engineering, software and designing tools, modeling, characterization and metrology) is not only necessary for maturing the field but also very much needed to spark new ideas.

To further facilitate this goal of exploring and pushing this new technology to its full potential, realizing the economic opportunity across multiple industries for service providers, systems manufacturers and photonics companies, and providing a realistic assessment of how digital manufacturing technology, applications, and markets will evolve in the near future; we assembled an industry panel on 3D Printing Manufacturing for the first time within the conference. Leaders from various areas gave their perspective and outlooks on this very exciting evolving field. Experts advised us to certify as we build products due to the prohibitive high cost of design change. They also warned us that business models will evolve and that the way of making products will be fundamentally changed. These changes will present challenges to current intellectual property laws. They will also bring concerns over the cyber security. Overall, this inaugural industry panel was well attended and received. It was a success.

Finally, we would like to thank all conference speakers, panelists, and attendees for their contribution to the conference. We hope that more people will come and share their work at this unique platform next year. After all, this is what this conference is all about — it is for you.

**Bo Gu**  
**Henry Helvajian**  
**Alberto Piqué**